

FDS8884

N-Channel PowerTrench® MOSFET

30V, 8.5A, 23mΩ

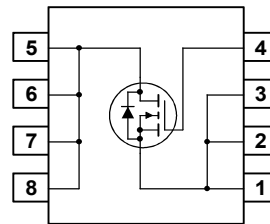
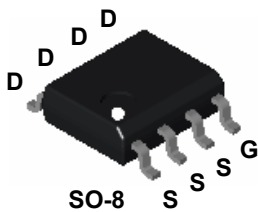
General Descriptions

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(on)}$ and fast switching speed.



Features

- Max $r_{DS(on)}$ = 23mΩ at $V_{GS} = 10V$, $I_D = 8.5A$
- Max $r_{DS(on)}$ = 30mΩ at $V_{GS} = 4.5V$, $I_D = 7.5A$
- Low gate charge
- 100% R_G Tested
- RoHS Compliant



MOSFET Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

| Symbol | Parameter | Ratings | Units |
|----------------|-----------------------------------|------------|-------|
| V_{DS} | Drain to Source Voltage | 30 | V |
| V_{GS} | Gate to Source Voltage | ± 20 | V |
| I_D | Drain Current Continuous | 8.5 | A |
| | Pulsed | 40 | A |
| E_{AS} | Single Pulse Avalanche Energy | 32 | mJ |
| P_D | Power dissipation | 2.5 | W |
| | Derate above 25°C | 20 | mW/°C |
| T_J, T_{STG} | Operating and Storage Temperature | -55 to 150 | °C |

Thermal Characteristics

| | | | | |
|-----------------|-----------------------------------------|-----------|----|------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | (Note 1a) | 50 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Case | (Note 1) | 25 | °C/W |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|---------|---------|-----------|------------|------------|
| FDS8884 | FDS8884 | SO-8 | 330mm | 12mm | 2500 units |

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

Off Characteristics

| | | | | | | |
|--------------------------------------|-------------------------------------------|-------------------------------------------------------------------------|----|----|-----------|----------------------|
| BV_{DSS} | Drain to Source Breakdown Voltage | $I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$ | 30 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\mu\text{A}$, referenced to 25°C | | 23 | | mV/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 24\text{V}$ $V_{GS} = 0\text{V}$ $T_J = 125^\circ\text{C}$ | | | 1 250 | μA |
| I_{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 20\text{V}$ | | | ± 100 | nA |

On Characteristics (Note 3)

| | | | | | | |
|----------------------------------------|----------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|----------------|----------------|----------------------|
| $V_{GS(th)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ | 1.2 | 1.7 | 2.5 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate to Source Threshold Voltage Temperature Coefficient | $I_D = 250\mu\text{A}$, referenced to 25°C | | -4.9 | | mV/ $^\circ\text{C}$ |
| $r_{DS(on)}$ | Drain to Source On Resistance | $V_{GS} = 10\text{V}, I_D = 8.5\text{A}$, $V_{GS} = 4.5\text{V}, I_D = 7.5\text{A}$, $V_{GS} = 10\text{V}, I_D = 8.5\text{A}$, $T_J = 125^\circ\text{C}$ | | 19 23 26 | 23 30 32 | m Ω |

Dynamic Characteristics

| | | | | | | |
|-----------|------------------------------|------------------------------------------------------------------|--|-----|-----|----------|
| C_{iss} | Input Capacitance | $V_{DS} = 15\text{V}, V_{GS} = 0\text{V}$, $f = 1\text{MHz}$ | | 475 | 635 | pF |
| C_{oss} | Output Capacitance | | | 100 | 135 | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 65 | 100 | pF |
| R_G | Gate Resistance | $f = 1\text{MHz}$ | | 0.9 | 1.6 | Ω |

Switching Characteristics (Note 3)

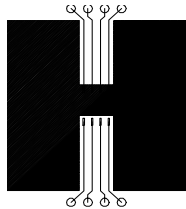
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|--------------|----------------------------|--------------------------------------------------------------------------------------|--|-----|----|----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 15\text{V}, I_D = 8.5\text{A}$ $V_{GS} = 10\text{V}, R_{GS} = 33\Omega$ | | 5 | 10 | ns |
| t_r | Rise Time | | | 9 | 18 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 42 | 68 | ns |
| t_f | Fall Time | | | 21 | 34 | ns |
| Q_g | Total Gate Charge | $V_{DS} = 15\text{V}, V_{GS} = 10\text{V}$ $I_D = 8.5\text{A}$ | | 9.2 | 13 | nC |
| Q_g | Total Gate Charge | $V_{DS} = 15\text{V}, V_{GS} = 5\text{V}$ | | 5.0 | 7 | nC |
| Q_{gs} | Gate to Source Gate Charge | $I_D = 8.5\text{A}$ | | 1.5 | | nC |
| Q_{gd} | Gate to Drain Charge | | | 2.0 | | nC |

Drain-Source Diode Characteristics

| | | | | | | |
|----------|-------------------------------|------------------------------------------------------|--|-----|------|----|
| V_{SD} | Source to Drain Diode Voltage | $I_{SD} = 8.5\text{A}$ | | 0.9 | 1.25 | V |
| | | $I_{SD} = 2.1\text{A}$ | | 0.8 | 1.0 | V |
| t_{rr} | Reverse Recovery Time | $I_F = 8.5\text{A}, di/dt = 100\text{A}/\mu\text{s}$ | | | 33 | ns |
| Q_{rr} | Reverse Recovery Charge | | | | 20 | nC |

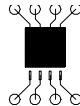
Notes:

1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

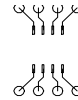


Scale 1 : 1 on letter size paper

a) $50^\circ\text{C}/\text{W}$ when mounted on a 1 in² pad of 2 oz copper



b) $105^\circ\text{C}/\text{W}$ when mounted on a .04 in² pad of 2 oz copper



c) $125^\circ\text{C}/\text{W}$ when mounted on a minimum pad

2: Starting $T_J = 25^\circ\text{C}$, $L = 1\text{mH}$, $I_{AS} = 8\text{A}$, $V_{DD} = 27\text{V}$, $V_{GS} = 10\text{V}$.
3: Pulse Test: Pulse Width <math><300\mu\text{s}</math>, Duty Cycle <math><2\%</math>.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

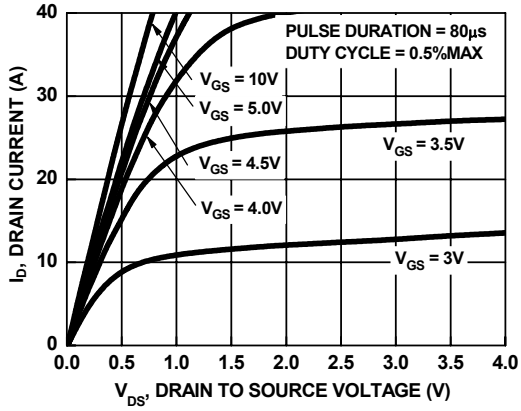


Figure 1. On Region Characteristics

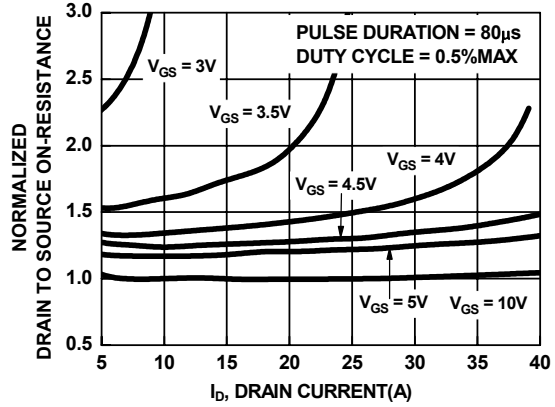


Figure 2. Normalized On-Resistance vs Drain current and Gate Voltage

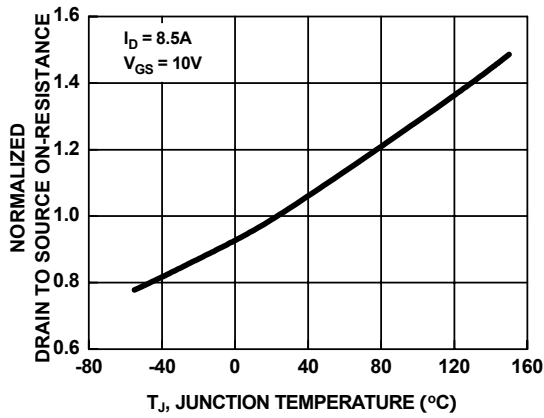


Figure 3. Normalized On Resistance vs Junction Temperature

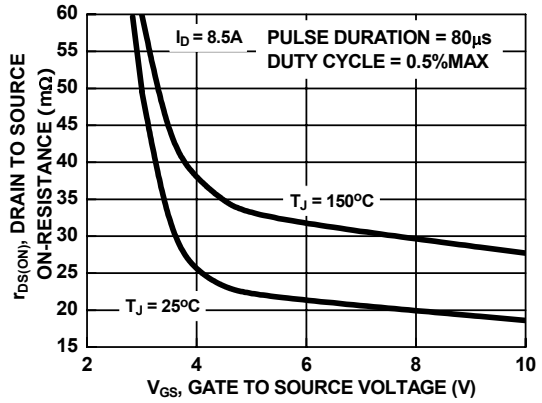


Figure 4. On-Resistance vs Gate to Source Voltage

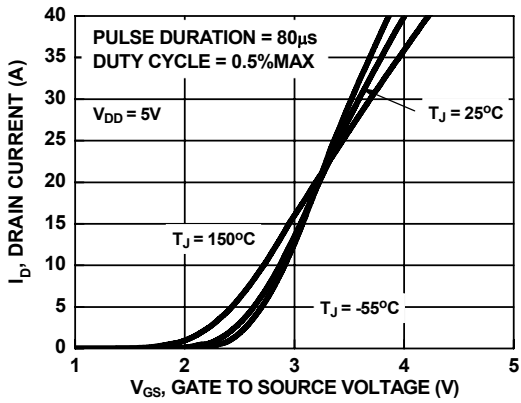


Figure 5. Transfer Characteristics

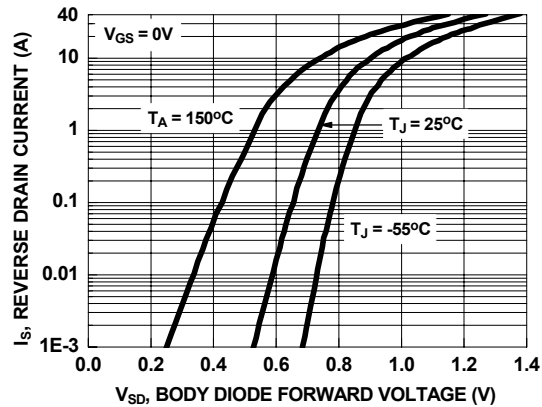


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

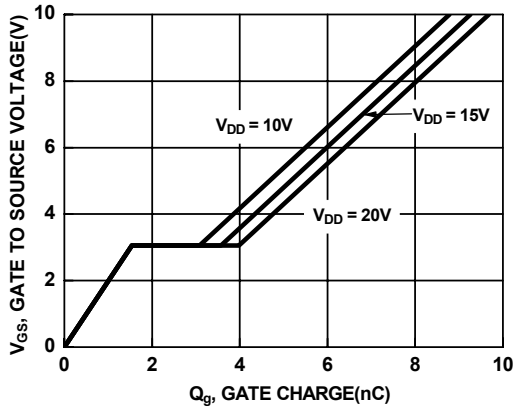


Figure 7. Gate Charge Characteristics

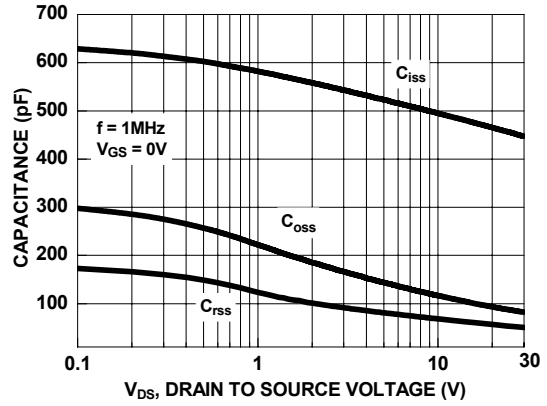


Figure 8. Capacitance vs Drain to Source Voltage

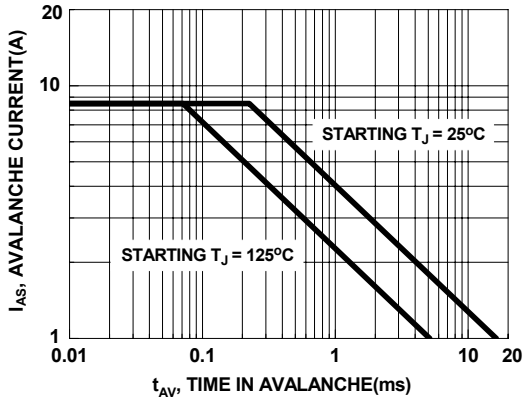


Figure 9. Unclamped Inductive Switching Capability

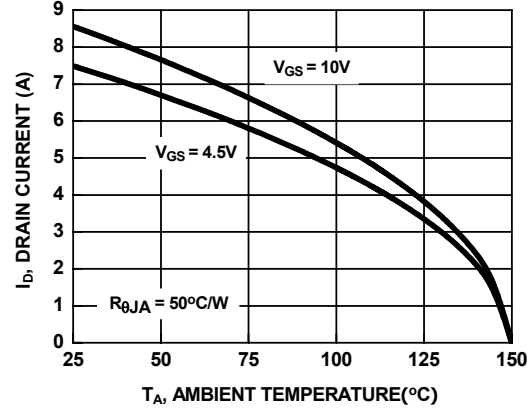


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

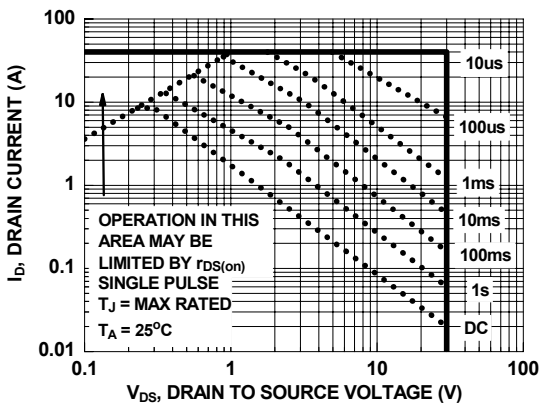


Figure 11. Forward Bias Safe Operating Area

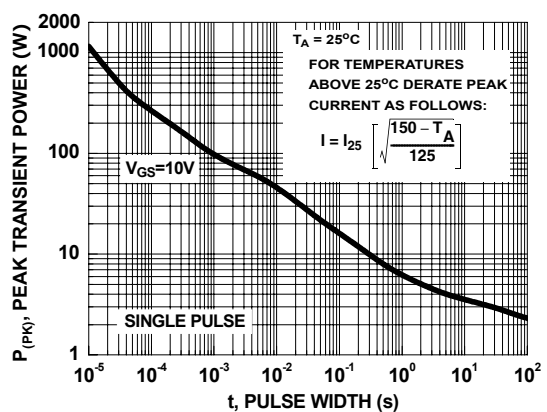


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

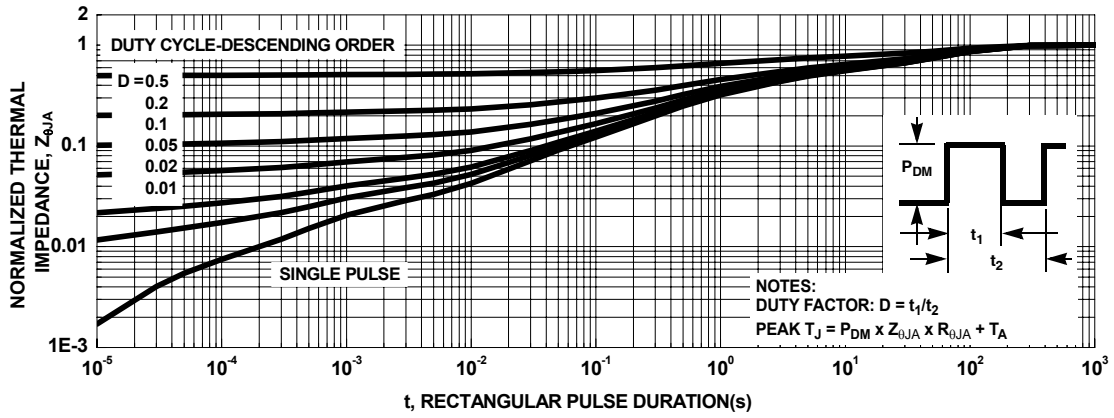


Figure 13. Transient Thermal Response Curve

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